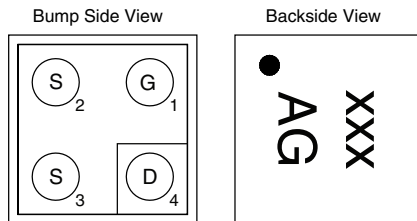




N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A) ^a	Q _g (Typ.)
20	0.059 at V _{GS} = 4.5 V	3.2	6.3 nC
	0.061 at V _{GS} = 3.7 V	3.1	
	0.065 at V _{GS} = 2.5 V	3.0	
	0.085 at V _{GS} = 1.8 V	2.7	

MICRO FOOT



Device Marking: xxx = Date/Lot Traceability Code
 AG = Device Marking Code

Ordering Information: Si8812DB-T2-E1 (Lead (Pb)-free and Halogen-free)

FEATURES

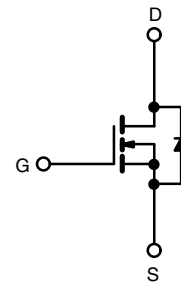
- TrenchFET[®] Power MOSFET
- Small 0.8 mm x 0.8 mm Outline Area
- Low 0.4 mm max. profile
- Low On-Resistance
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912



RoHS
 COMPLIANT
 HALOGEN
 FREE

APPLICATIONS

- Load Switch with Low Voltage Drop
- Power Management
- For Smart Phones, Tablet PCs, Mobile Computing



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	± 8	
Continuous Drain Current (T _J = 150 °C)	I _D	T _A = 25 °C	3.2 ^a
		T _A = 70 °C	2.6 ^a
		T _A = 25 °C	2.3 ^b
		T _A = 70 °C	1.8 ^b
Pulsed Drain Current (t = 300 μs)	I _{DM}	20	A
Continuous Source-Drain Diode Current	I _S	T _A = 25 °C	
		T _A = 25 °C	0.4 ^b
Maximum Power Dissipation	P _D	T _A = 25 °C	0.9 ^a
		T _A = 70 °C	0.6 ^a
		T _A = 25 °C	0.5 ^b
		T _A = 70 °C	0.3 ^b
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) ^c		260	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, d}	R _{thJA}	105	135	°C/W
Maximum Junction-to-Ambient ^{b, e}		200	260	

Notes:

- Surface mounted on 1" x 1" FR4 board with full copper, t = 5 s.
- Surface mounted on 1" x 1" FR4 board with minimum copper, t = 5 s.
- Refer to IPC/JEDEC (J-STD-020), no manual or hand soldering.
- Maximum under steady state conditions is 185 °C/W.
- Maximum under steady state conditions is 330 °C/W.

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	20			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		29		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 2.6		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	0.4		1	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 8\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}$, $V_{GS} = 4.5\text{ V}$	10			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}$, $I_D = 1\text{ A}$		0.048	0.059	Ω
		$V_{GS} = 3.7\text{ V}$, $I_D = 1\text{ A}$		0.049	0.061	
		$V_{GS} = 2.5\text{ V}$, $I_D = 1\text{ A}$		0.052	0.065	
		$V_{GS} = 1.8\text{ V}$, $I_D = 0.5\text{ A}$		0.060	0.085	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10\text{ V}$, $I_D = 1\text{ A}$		12		S
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 10\text{ V}$, $V_{GS} = 8\text{ V}$, $I_D = 1\text{ A}$		11	17	nC
		$V_{DS} = 10\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 1\text{ A}$		6.3	10	
Gate-Source Charge	Q_{gs}	$V_{DS} = 10\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 1\text{ A}$		0.8		nC
Gate-Drain Charge	Q_{gd}			1.4		
Gate Resistance	R_g	$f = 1\text{ MHz}$		6		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10\text{ V}$, $R_L = 10\text{ }\Omega$ $I_D \cong 1\text{ A}$, $V_{GEN} = 4.5\text{ V}$, $R_g = 1\text{ }\Omega$		10	20	ns
Rise Time	t_r			13	25	
Turn-Off Delay Time	$t_{d(off)}$			33	60	
Fall Time	t_f			10	20	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10\text{ V}$, $R_L = 10\text{ }\Omega$ $I_D \cong 1\text{ A}$, $V_{GEN} = 8\text{ V}$, $R_g = 1\text{ }\Omega$		5	10	
Rise Time	t_r			11	20	
Turn-Off Delay Time	$t_{d(off)}$			25	50	
Fall Time	t_f			10	20	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_A = 25\text{ }^\circ\text{C}$			0.7	A
Pulse Diode Forward Current	I_{SM}				20	
Body Diode Voltage	V_{SD}	$I_S = 1\text{ A}$, $V_{GS} = 0\text{ V}$		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 1\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$		10	20	ns
Body Diode Reverse Recovery Charge	Q_{rr}			3	10	nC
Reverse Recovery Fall Time	t_a			6		ns
Reverse Recovery Rise Time	t_b			4		

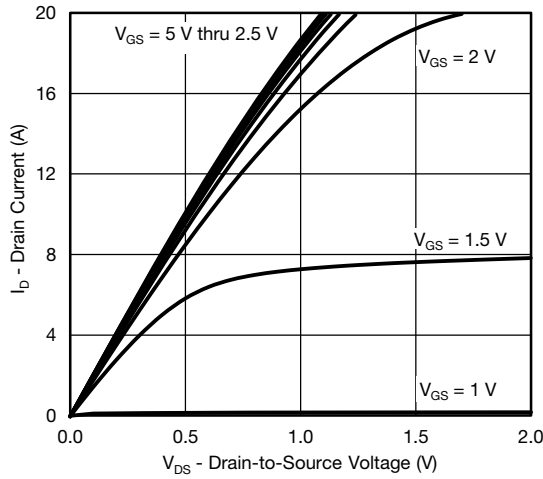
Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing.

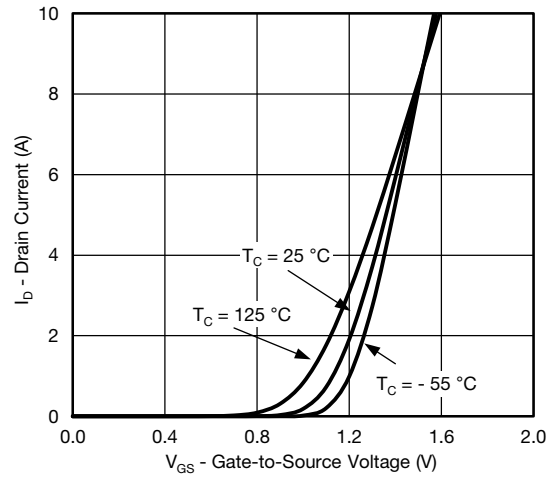
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



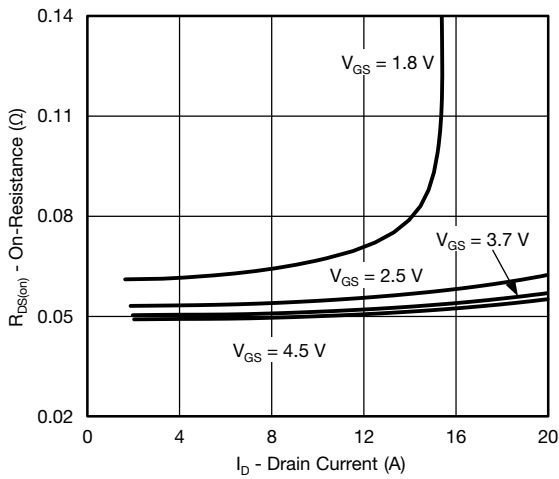
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



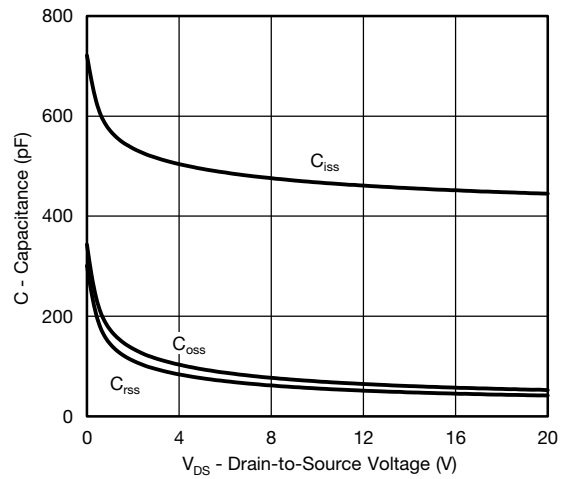
Output Characteristics



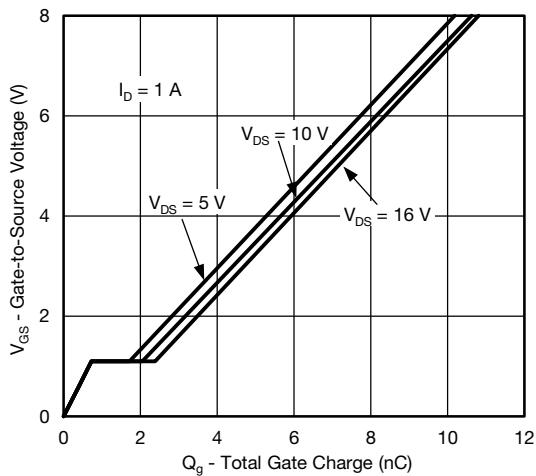
Transfer Characteristics



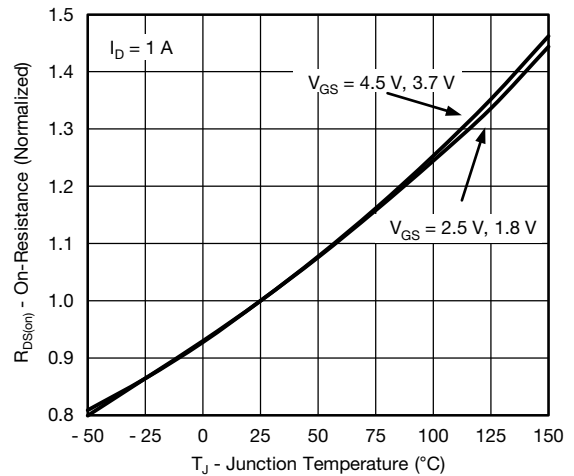
On-Resistance vs. Drain Current



Capacitance

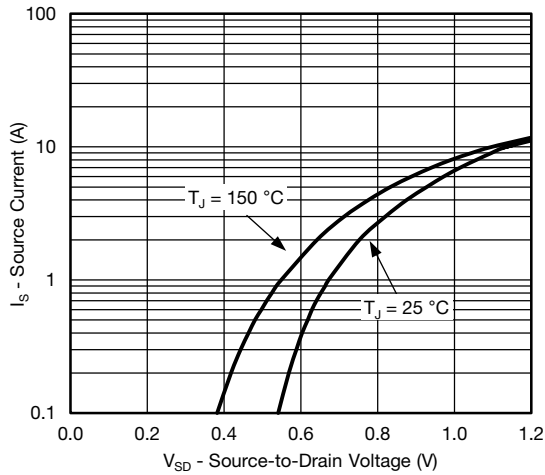


Gate Charge

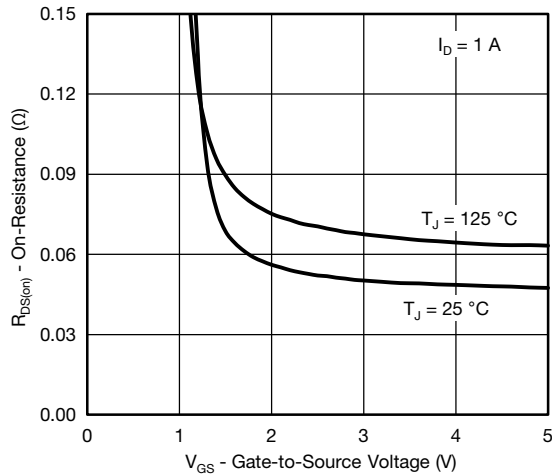


On-Resistance vs. Junction Temperature

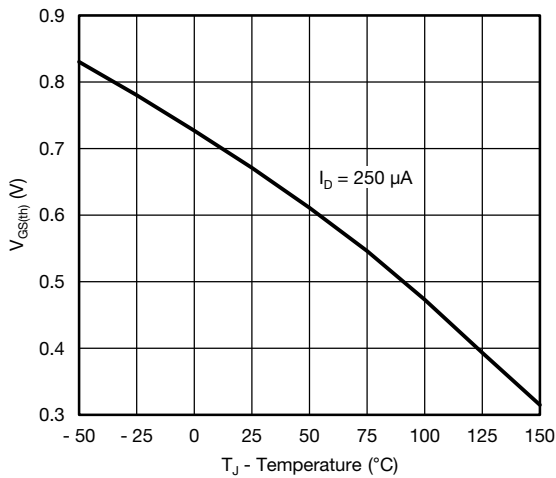
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



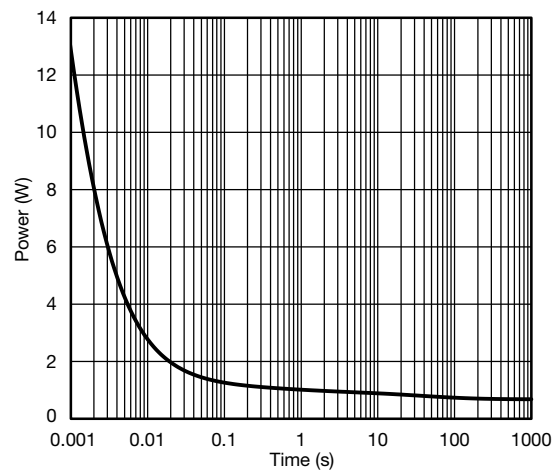
Source-Drain Diode Forward Voltage



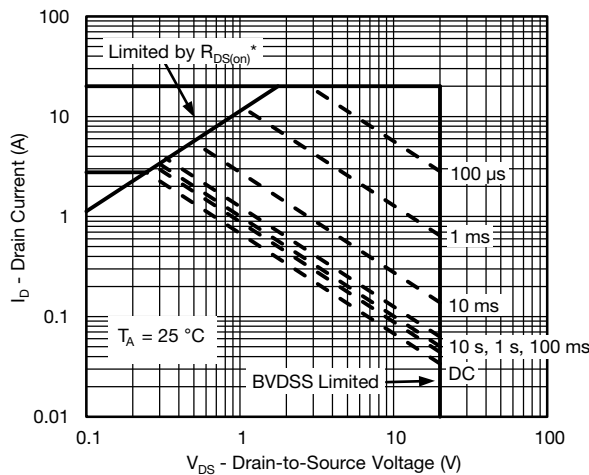
On-Resistance vs. Gate-to-Source Voltage



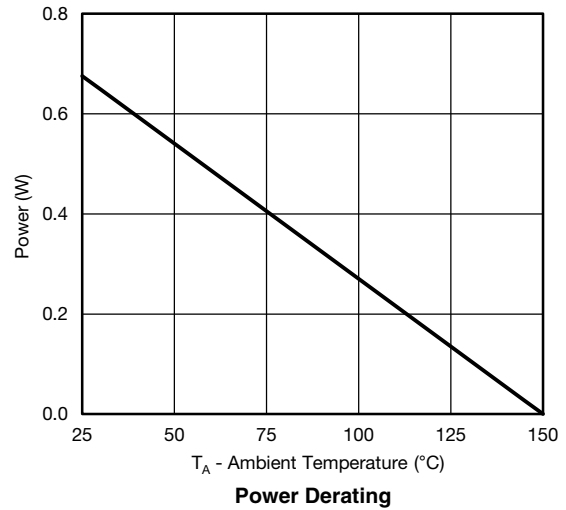
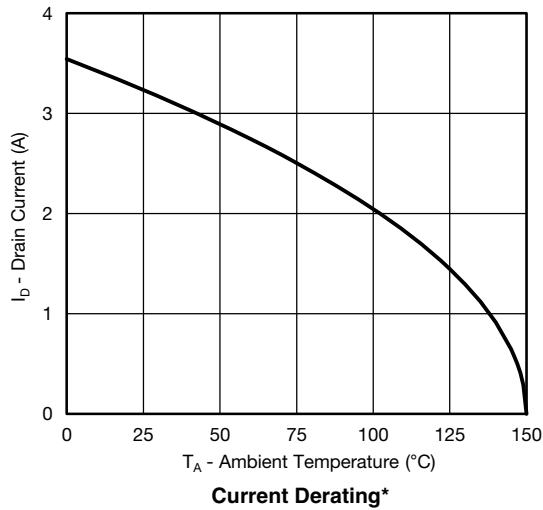
Threshold Voltage



Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient

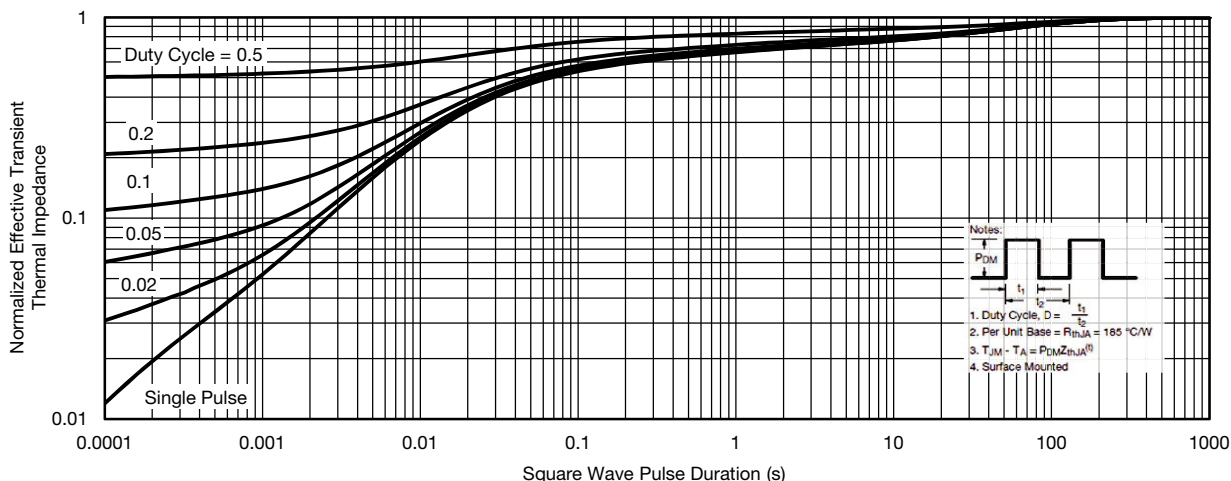

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


Note:

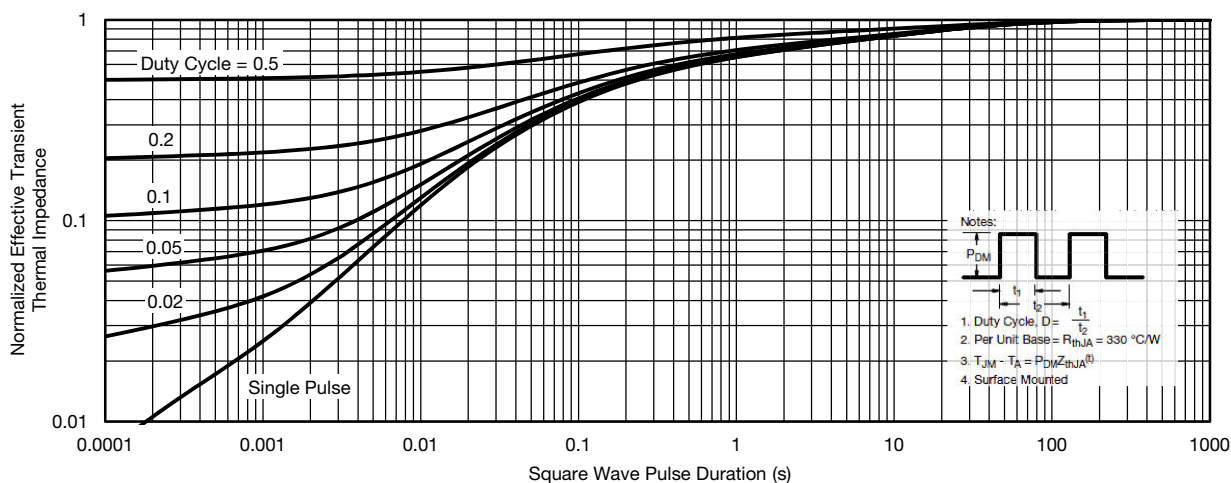
When mounted on 1" x 1" FR4 with full copper.

* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-ambient thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient (On 1" x 1" FR4 board with maximum copper)

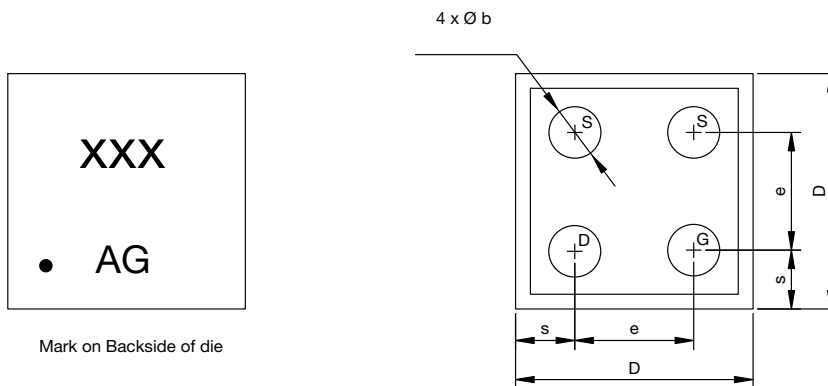


Normalized Thermal Transient Impedance, Junction-to-Ambient (On 1" x 1" FR4 board with minimum copper)



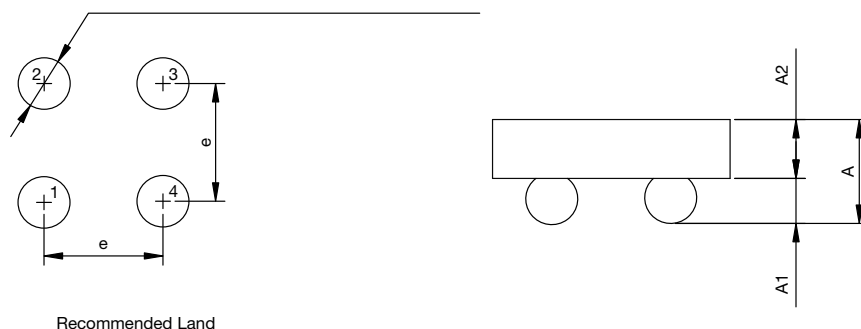
PACKAGE OUTLINE

MICRO FOOT 0.8 mm x 0.8 mm: 4-BUMP (2 x 2, 0.4 mm PITCH)



Mark on Backside of die

4 x Ø 0.205 to 0.225 Note 4
Solder Mask ~ Ø 0.215



Recommended Land

Notes (Unless otherwise specified):

1. All dimensions are in millimeters.
2. Four (4) solder bumps are lead (Pb)-free 95.5Sn/3.5Ag/0.7Cu with diameter Ø 0.165 mm to Ø 0.185 mm.
3. Backside surface is coated with a Ti/Ni/Ag layer.
4. Non-solder mask defined copper landing pad.
5. • is location of pin 1.

Dim.	Millimeters ^a			Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.314	0.357	0.400	0.0124	0.0141	0.0157
A ₁	0.127	0.157	0.187	0.0050	0.0062	0.0074
A ₂	0.187	0.200	0.213	0.0074	0.0079	0.0084
b	0.165	0.175	0.185	0.0064	0.0068	0.0072
e		0.400			0.0157	
s	0.180	0.200	0.220	0.0070	0.0078	0.0086
D	0.760	0.800	0.840	0.0299	0.0314	0.0330

Notes:

- a. Use millimeters as the primary measurement.

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